Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Kingbright

3.2mm x 1.6mm FULL-COLOR SURFACE MOUNT LED LAMP

Part Number: APTF3216SEEZGQBDC

Hyper Red
Green
Blue

ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

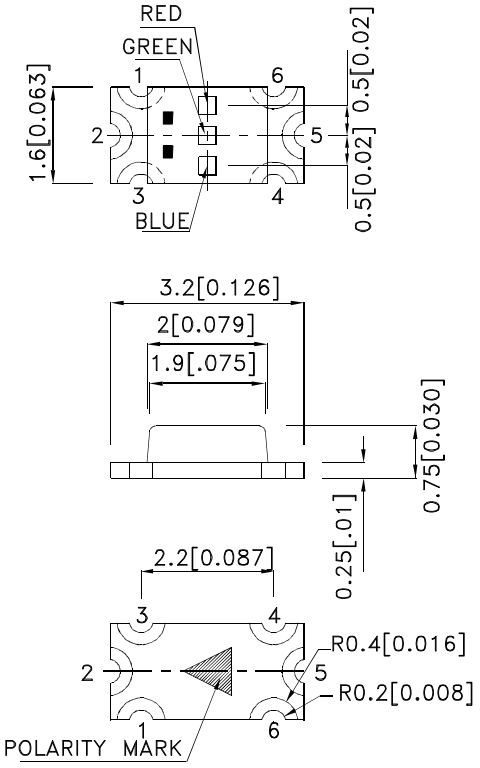
Features

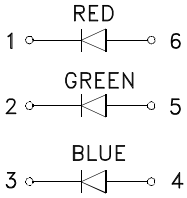
- 3.2mmx1.6mm SMT LED, 0.75mm thickness.
- Low power consumption.
- Can produce any color in visible spectrum, including white light.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

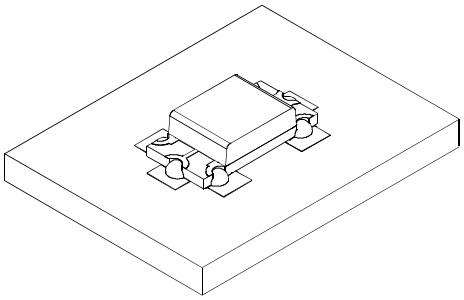
Description

The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.
The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
The Blue source color devices are made with InGaN Light Emitting Diode.
Static electricity and surge damage the LEDS.
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
All devices, equipment and machinery must be electrically grounded.

Package Dimensions







Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.2(0.008") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APTF3216SEEZGQBDC	Hyper Red (AlGaInP)	Water Clear	200	400	120°
	Green (InGaN)		200	350	
	Blue (InGaN)		55	80	

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

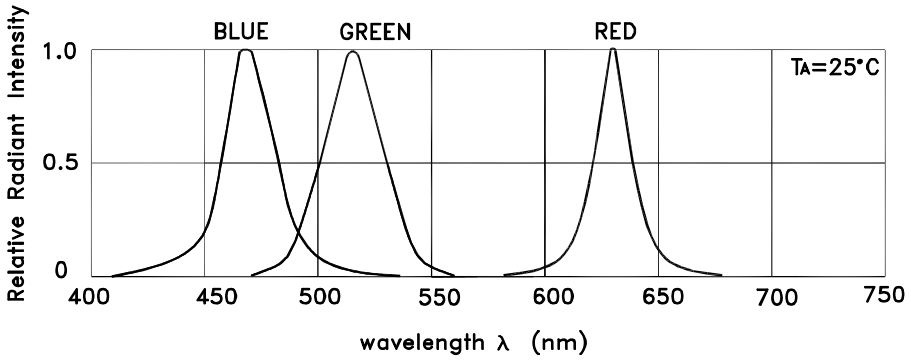
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green Blue	630 515 468		nm	I_F=20mA
λD [1]	Dominant Wavelength	Hyper Red Green Blue	621 525 470		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green Blue	20 30 25		nm	I_F=20mA
C	Capacitance	Hyper Red Green Blue	25 45 100		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Hyper Red Green Blue	2 3.3 3.3	2.5 4.1 4	V	I_F=20mA
I_R	Reverse Current	Hyper Red Green Blue		10 50 50	uA	V_R=5V

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

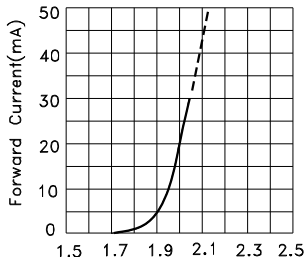
Parameter	Hyper Red	Green	Blue	Units
Power dissipation	75	102.5	120	mW
DC Forward Current	30	25	30	mA
Peak Forward Current [1]	195	150	150	mA
Reverse Voltage	5			V
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

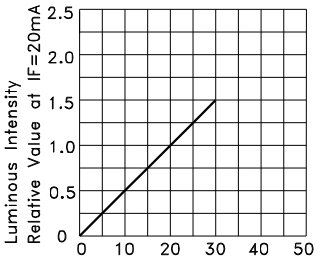


RELATIVE INTENSITY Vs. WAVELENGTH

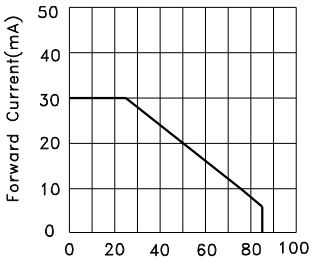
APTF3216SEEZGQBDC
Hyper Red



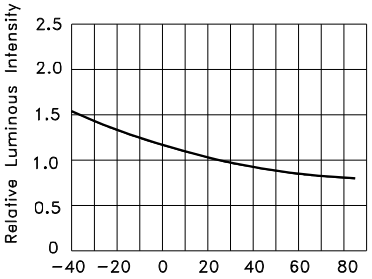
FORWARD CURRENT Vs.
FORWARD VOLTAGE



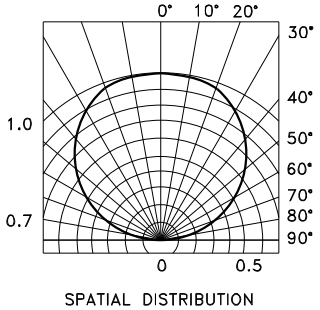
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE

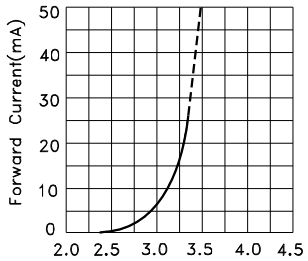


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

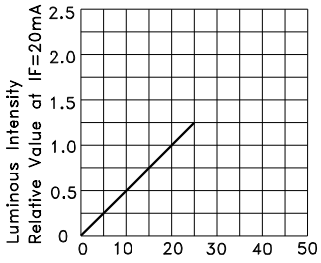


SPATIAL DISTRIBUTION

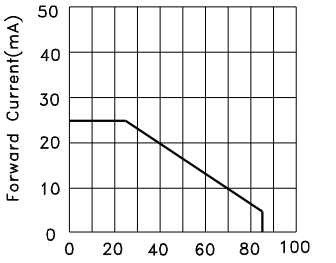
Green



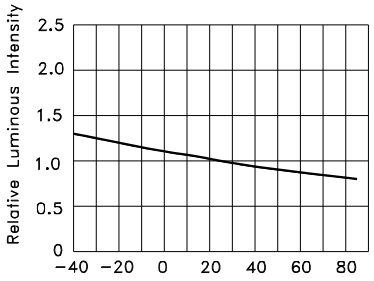
FORWARD CURRENT Vs.
FORWARD VOLTAGE



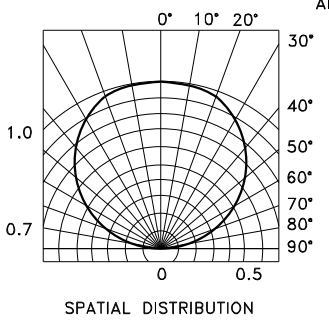
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE

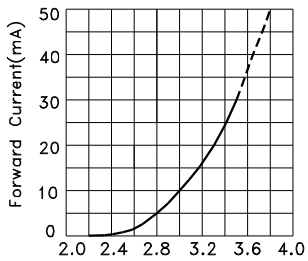


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

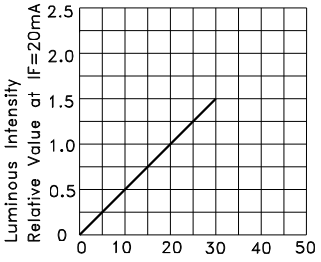


SPATIAL DISTRIBUTION

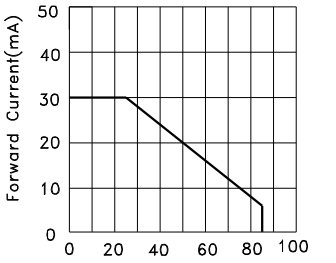
Blue



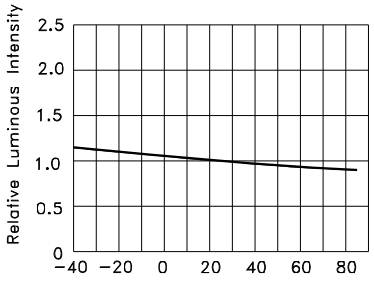
FORWARD CURRENT Vs.
FORWARD VOLTAGE



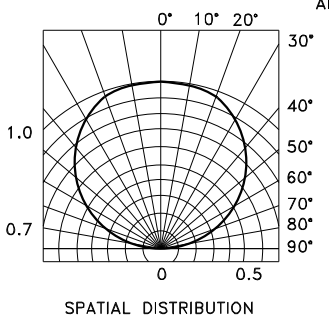
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

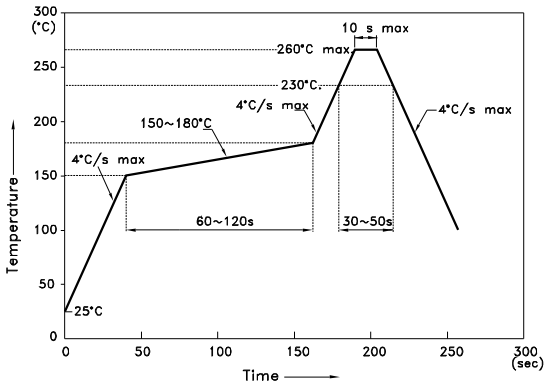


SPATIAL DISTRIBUTION

APTF3216SEEZGQBDC

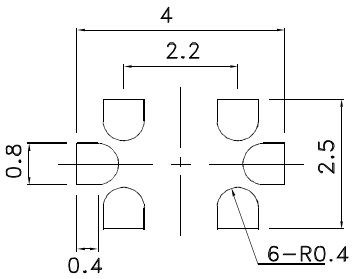
Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

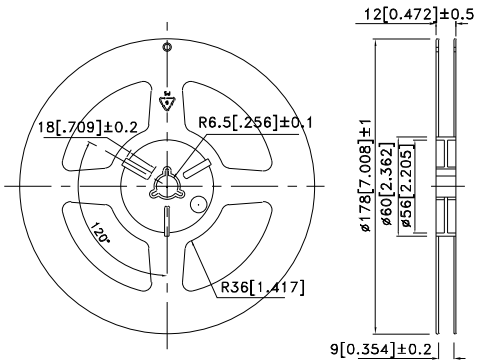


NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

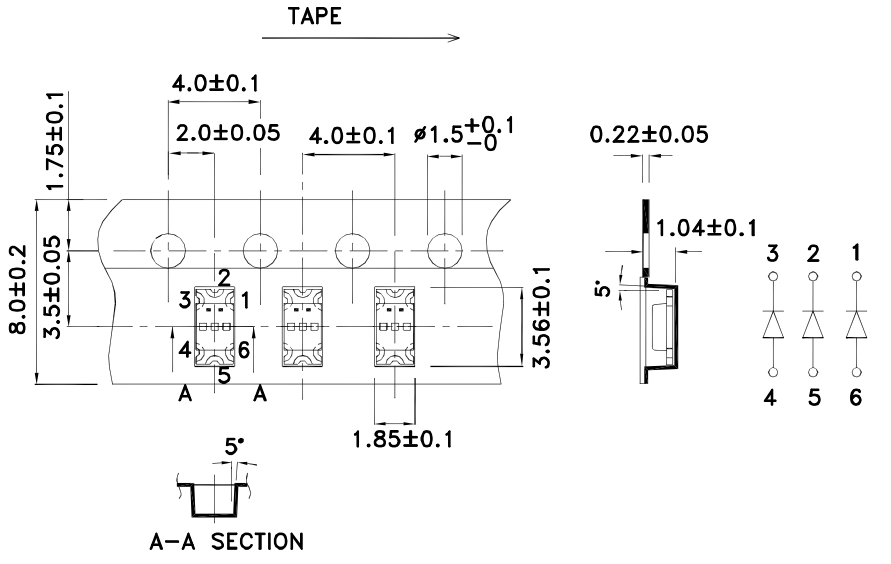
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Dimensions (Units : mm)



Kingbright

PACKING & LABEL SPECIFICATIONS **APTF3216SEEZGQBDC**